



SMD Low Profile High Current Molded Inductor

Low loss realized with low DCR.

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100% Lead(Pb)-Free and RoHS compliant.

High performance (Isat) realized by metal dust core.

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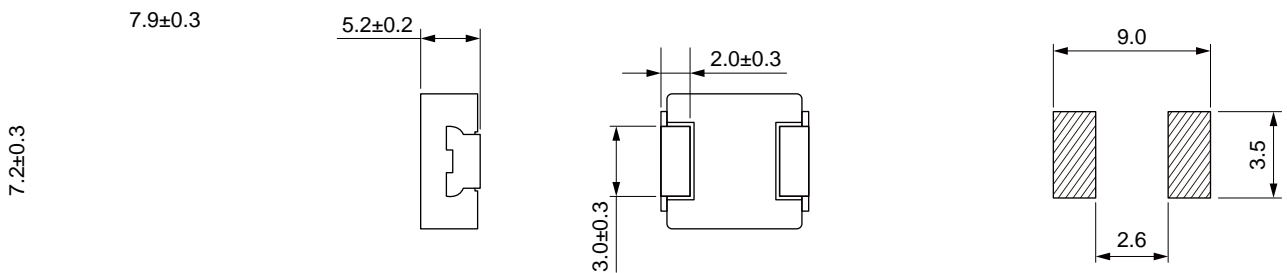
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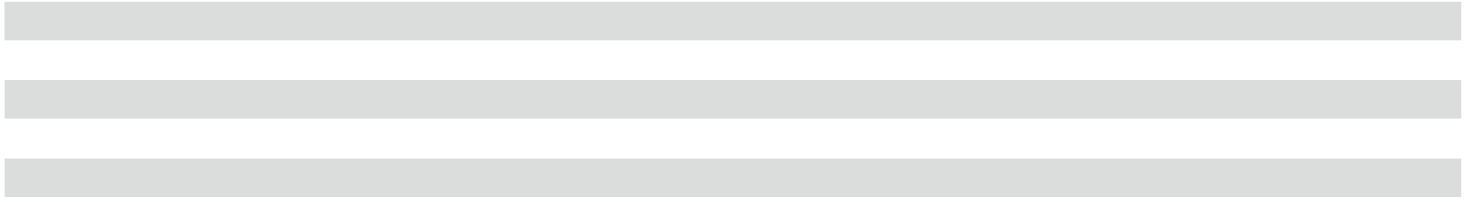
HVAC

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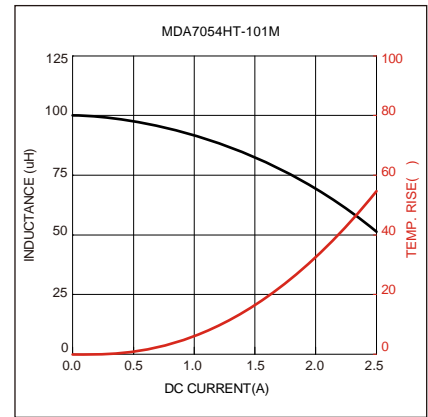
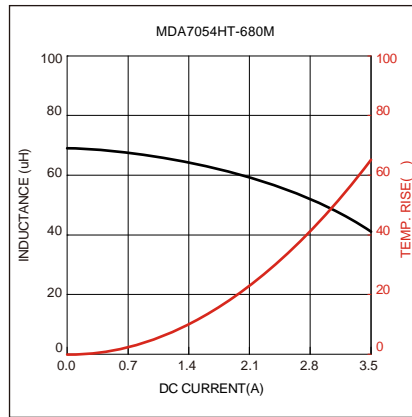
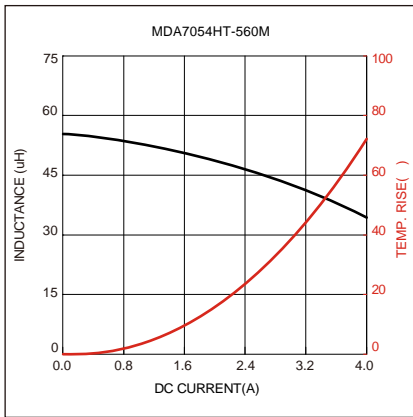
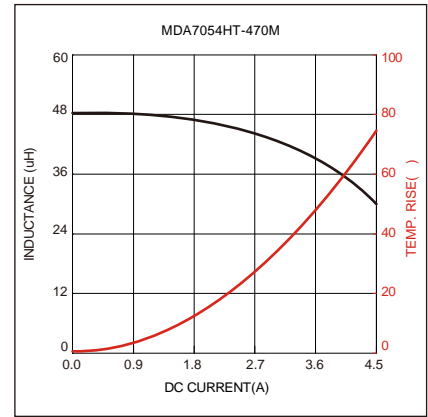
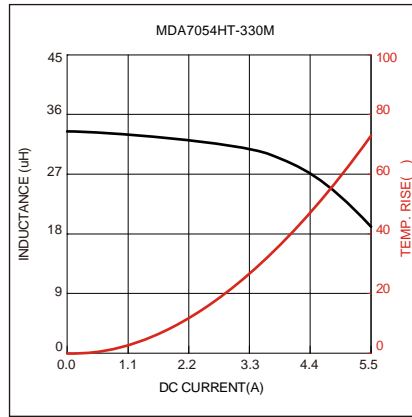
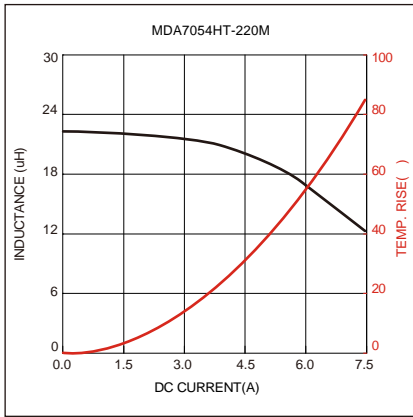
Audio subsystem



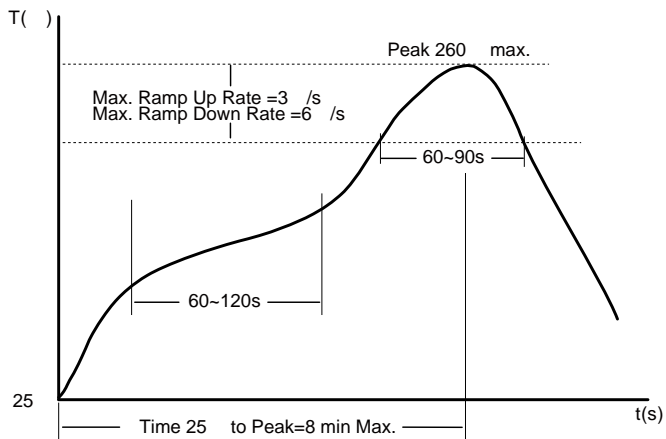
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.
MDA7054HT-1R5M	1.50	±20%	11.5	10.3	16.4	14.0	6.30	7.30
MDA7054HT-2R2M	2.20	±20%	9.80	8.70	15.0	12.7	9.90	11.4
MDA7054HT-3R3M	3.30	±20%	8.00	7.20	13.5	11.6	13.4	15.4
MDA7054HT-4R7M	4.70	±20%	7.00	6.30	13.2	11.2	18.2	20.9
MDA7054HT-5R6M	5.60	±20%	6.50	5.60	10.6	9.20	20.0	24.0
MDA7054HT-6R8M	6.80	±20%	6.20	5.50	10.2	8.70	23.1	26.6
MDA7054HT-8R2M	8.20	±20%	5.80	5.00	9.20	7.70	27.8	31.9
MDA7054HT-100M	10.0	±20%	5.20	4.70	8.10	6.90	33.0	38.0
MDA7054HT-150M	15.0	±20%	3.80	3.40	7.00	5.90	60.0	66.0
MDA7054HT-220M	22.0	±20%	3.30	3.00	6.30	5.40	85.0	93.5



Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200 / 60~120 sec.

Allowed time above 217 : 60~90 sec.

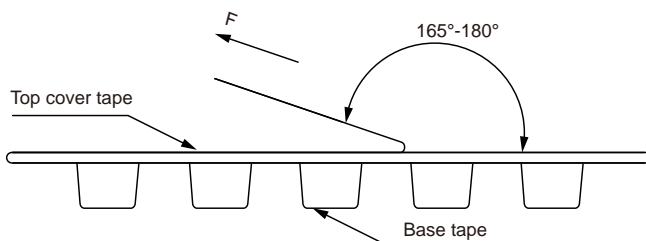
Max temperature: 260 .

Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Peel force of top cover tape:

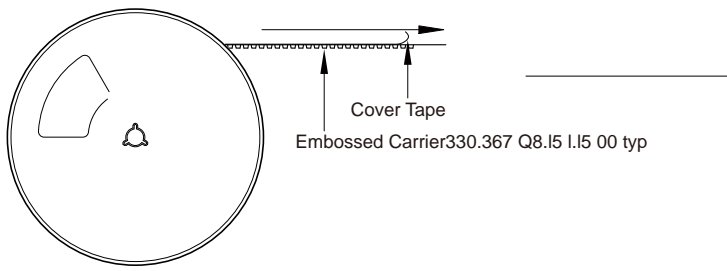


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing Inductance+period)
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Reel Dimension : [mm]



Packaging Quantity: